



### CORPORATE HIGHLIGHTS

Mr. Chris Borch, CEO

Mr. Low Ming Wah, COO





### Corporate Overview





- Founded in 1983 in Singapore by CEO Chris Borch
- Listed on the Singapore Exchange (Main Board) since 2003
- Design and manufacture high precision tools, parts and assemblies for the semiconductor, medical, aerospace and other high technology industries
- Serve a worldwide base of customers from six facilities in Asia and the USA
- Two business segments:
  - Semiconductor tooling business serves nearly all the chip manufacturers/assembly and test companies
  - Custom Machining & Assembly (CMA) division serves capital equipment makers
- Committed to generating shareholder returns





Micro-Mechanics Holdings (Headquarters) Sales & Manufacturing

Sales & Manufacturing

Sales

### High Precision Tools for Semiconductor A&T





Rubber and Plastic Pick-up Tips Ejector Needles & Needle Holders Dispensing Nozzles

Wire bond clamps
Wedges
Wire cutters
Electronic Flame Offs

#### **CONSUMABLE PRODUCTS**

require regular replacement

#### **HUNDREDS OF CUSTOMERS**

in chip assembly & testing sector

#### **FOCUS ON CYCLE TIME**

from customer inquiry to delivery

#### **BROAD PRODUCT RANGE**

backed by strong proprietary know-how

#### **RAISING BARRIERS**

from developing finer tools in line with chip package miniaturization

# Custom Machining & Assembly (CMA)



Precision and complex parts / assemblies for Tier-1 capital equipment manufacturers







### 24/7 MACHINING

Maximising 168 available hours Zero online tool and fixture set-up Repeatable processes

### INCREASED COMPETITIVENESS

to meet customer needs' in volatile marketplace

#### **DIVERSIFICATION**

into other high-tech industries

#### **GREATER REVENUE SCALABILITY**

than semiconductor tooling business



Semiconductor / Wafer Fabrication

Laser

Medical

Aerospace

### 1H14 Highlights

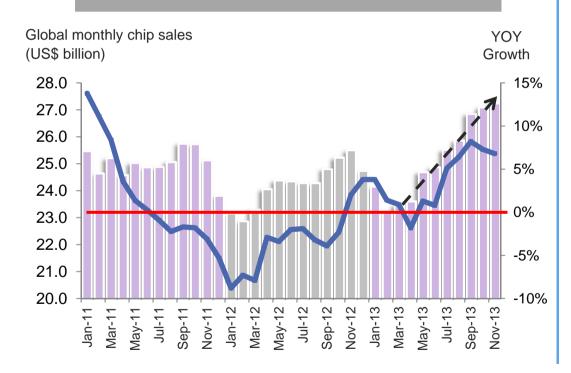


- Global chip industry recorded its **9TH** consecutive month of sales growth in November 2013
- Group's topline grew 12% driven by two consecutive quarters of YOY growth
- Investments in new equipment and productivity programs translating into positive operating results
- Tight expense control resulted in higher operating leverage
- Net Profit increased faster by 63.2% net profit margin widened to 16.3%
- Interim dividend of 1 cent per share total of 32.9 cents since IPO

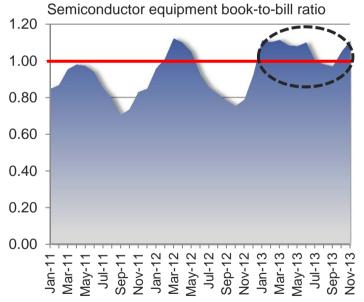
### **Industry Landscape**



Global semiconductor annual sales on track to exceed US\$300B for the first time ever in 2013



"The continuing rise in equipment bookings clearly points to year-end order activity that is substantially stronger compared to one year ago"



### **Investments Generating Results**



#### **INVESTED S\$16M**

in new equipment since FY2011

#### HIGHER AUTOMATION

and continual initiatives to enhance efficiency and capabilities

#### **CMA R&D PROJECT**

Developing 24/7 Machining Line

#### **24/7 FUNDAMENTALS**

being introduced to factories in Asia to enhance productivity

#### **IMPROVE**

Quality, Cost, Cycle Time & Manufacturing Flexibility



Perfect Parts and Tools, On-Time, Every Time

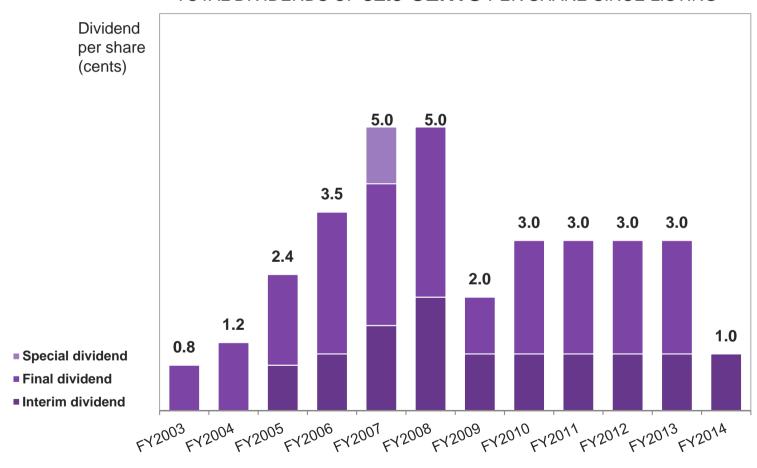
based on scalable, repeatable and costeffective processes



### Shareholder Value



#### TOTAL DIVIDENDS OF 32.9 CENTS PER SHARE SINCE LISTING







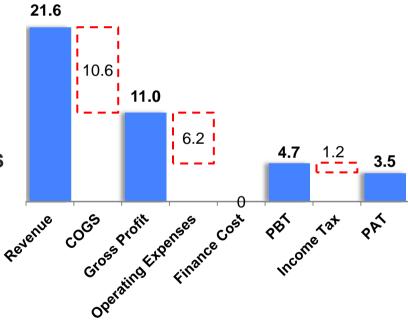


### 1H14 in Review



1H14 P&L Overview (S\$ million)

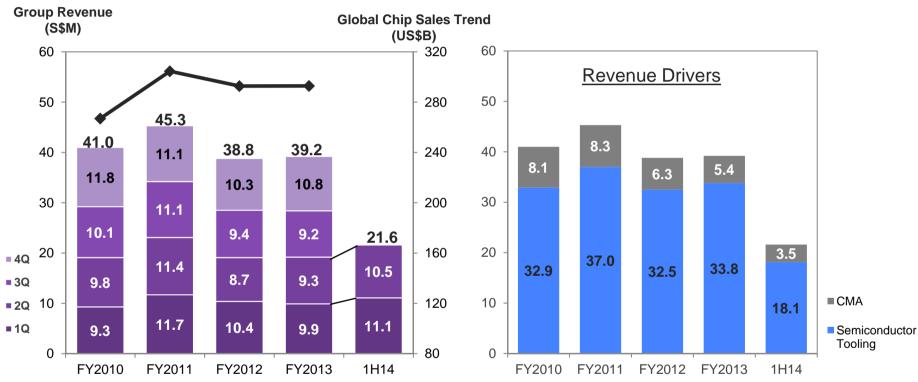
- **REVENUE UP 12.4%**
- GROSS PROFIT MARGIN EXPANDED TO 50.8%
- NET PROFIT UP 63.2%
- EPS IMPROVED TO 2.53 CENTS FROM 1.55 CENTS
- SOUND BALANCE SHEET WITH CASH OF \$\$10.0 MILLION AND ZERO DEBT



### Group Revenue

1H14 SALES UP 12.4%



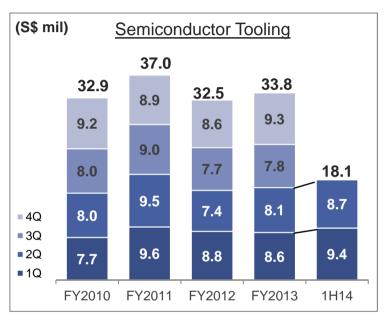


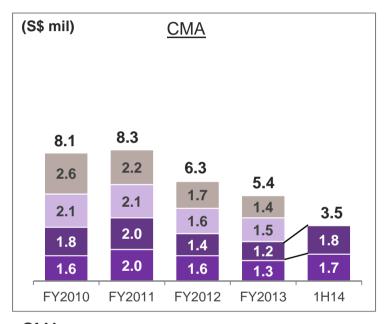
Global Chip Sales Trend according to FY. Data from Semiconductor Industry Association (SIA)

FY: Financial year ending 30 June

# Quarterly Revenue By Business Segments

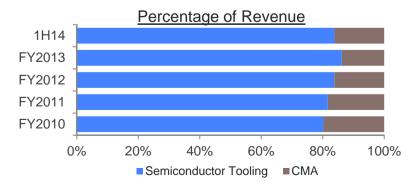
#### **TOOLING AND CMA SALES IMPROVED IN 1H14**





Semiconductor tooling +8.4%

CMA +39.8%



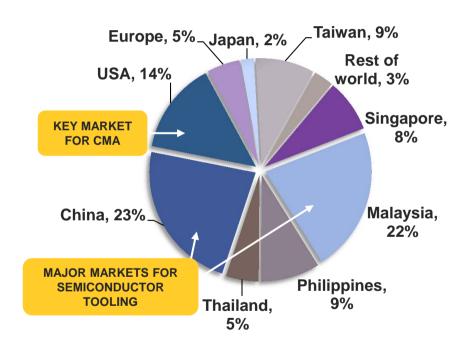


## Revenue by Geographical Market

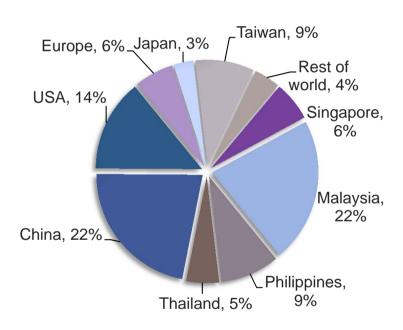
#### **DIVERSIFIED REVENUE STREAMS**



#### Sales Breakdown for 1H14



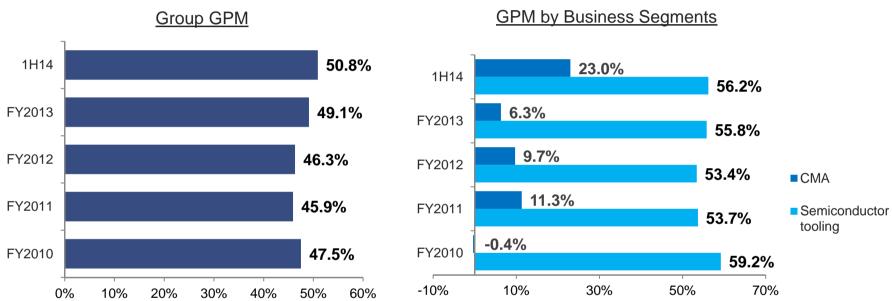
#### Sales Breakdown for 1H13



### **Gross Profit Margin**

#### **MARGIN EXPANSION IN 1H14**





#### **Semiconductor tooling**

GPM improved to 56.2% in 1H14 despite the constant price pressures typical of the semiconductor industry

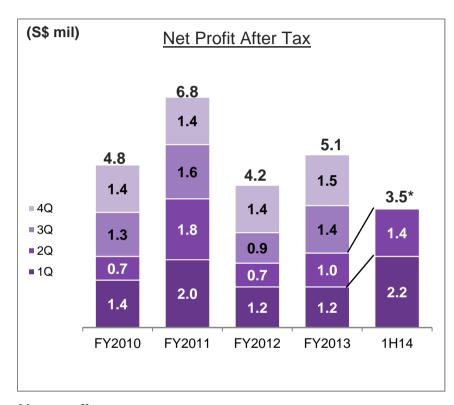
#### **CMA**

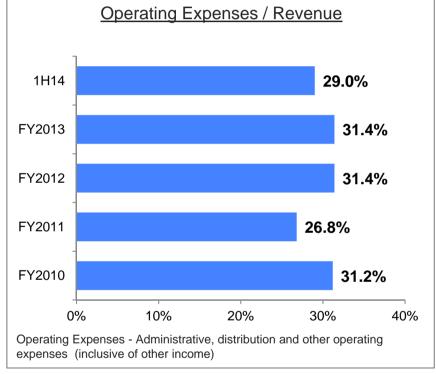
GPM improved to 23.0% due to increased sales and improved operational efficiency of our factory in the USA

### **Group Net Profit**

#### 1H14 PROFIT JUMPED 63.2%







### **Net profit**

1H14 profit rose on higher sales, increased GPM and tight control of expenses

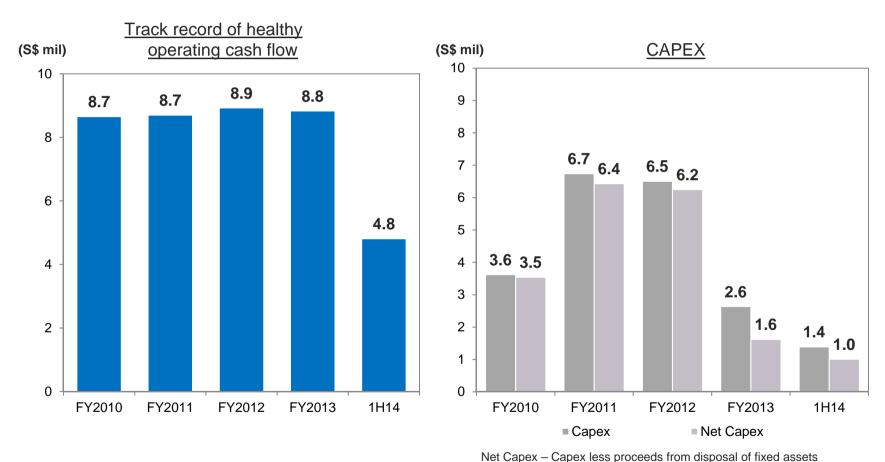
Two consecutive quarters of profit growth

Admin, Distribution and Other Operating expenses increased only 3.6% y-o-y (excl. other income)

<sup>\*</sup>Difference in total figure due to rounding

# Operating Cash Flow and CAPEX





18

### **Balance Sheet**



		31 Dec 2013	30 June 2013
Cash	Cash and cash equivalents	S\$10.0M#	S\$9.2M
Gearing	Total borrowings	Nil	Nil
<u>Trade</u> <u>Receivables</u>	(Outstanding > 90days) / Total trade receivables Bad debt expense	0.0% (1H14) S\$7.8k (1H14)	0.2% (FY13) Nil (FY13)
Inventory	Inventory / Sales Inventory write-off	5.8% (1H14) S\$60k (1H14)	5.5% (FY13) S\$72k (FY13)
<u>Equity</u>	Shareholders' equity NAV per share	S\$38.3M# 27.54 cents	S\$37.9M 27.29 cents

<sup>\*</sup>Paid dividends of S\$2.8M (Final dividend for FY2013)



# OUTLOOK

Mr. Chris Borch, CEO

Mr. Low Ming Wah, COO

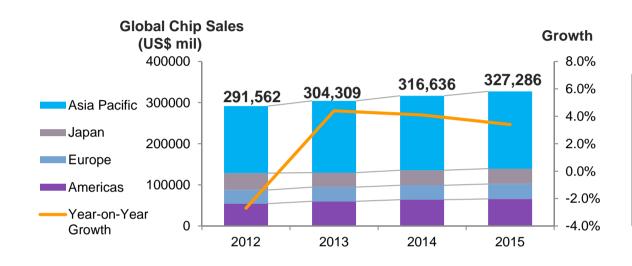


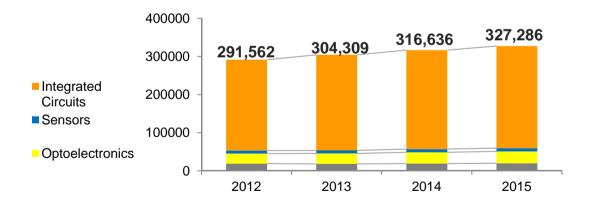




### **Industry Outlook**







#### WSTS Autumn 2013 Forecasts

**4.4%** growth in 2013

**4.1%** growth in 2014

**3.4%** growth in 2015

"The global industry notched its ninth consecutive month of increasing sales in November... Buoyed by sustained growth in the Americas and Asia Pacific and a recent rebound in Europe and Japan, the global semiconductor industry has shown increasing strength in 2013 and is on pace for record revenue. With solid momentum across all regions and most product categories, the industry is well-positioned for a strong start to the new year."

-- SIA Press Release, 3 January 2014

### **Group Outlook and Plans**

#### OPERATING ENVIRONMENT REMAINS VOLATILE

- External headwinds and limited business visibility
- Cost, price and delivery lead time pressures





- Continue shifting towards automated processes
- Leverage strengths in proprietary design and materials to develop consumable tools for changing market needs

#### **CMA**

- Continue to develop 24/7 Machining and improve unique recipe for repeatable, scalable and costeffective machining
- · Building stable customer base in USA

#### **INVESTMENTS**

- CAPEX around S\$4M for FY2014
- People and Processes *MMUniversity*



### **Investment Merits**



#### RECURRING INCOME STREAMS FROM PRECISION CONSUMABLE PRODUCTS

• Steady foundation and cost-effective operations which lead to high gross profit margin

#### **CASH-GENERATIVE MODEL WITH NO DEBT**

· Sound management of balance sheet and sensible cost structure

#### LONG TRACK RECORD OF DIVIDENDS

• Total dividends of over S\$40M since public listing

#### POSITIONED TO RIDE ON SEMICONDUCTOR INDUSTRY RECOVERY

- Tooling business correlates with the volume of chip production
- Developing CMA business to be a future growth catalyst

### Safe Harbour for Forward-Looking Statements



This presentation contains certain statements that are not statements of historical fact, i.e. forward-looking statements. Investors can identify some of these statements by forward-looking items such as 'expect', 'believe', 'plan', 'intend', 'estimate', 'anticipate', 'may', 'will', 'would', and 'could' or similar words. However, you should note that these words are not the exclusive means of identifying forward-looking statements. These forward-looking statements are based on current expectations, projections and assumptions about future events. Although Micro-Mechanics (Holdings) Ltd. believes that these expectations, projections, and assumptions are reasonable, these forward-looking statements are subject to the risks (whether known or unknown), uncertainties and assumptions about Micro-Mechanics (Holdings) Ltd. and its business operations.

Some of the key factors that could cause such differences are, among others, the following:

- changes in the political, social and economic conditions and regulatory environment in the jurisdictions where we conduct business or expect to conduct business;
- the risk that we may be unable to realise our anticipated growth strategies and expected internal growth;
- changes in and new developments in technologies and trends;
- changes in currency exchange rates;
- changes in customer preferences and needs;
- changes in competitive conditions in the semiconductor industry and our ability to compete under these conditions;
- changes in pricing for our products; and
- changes in our future capital needs and the availability of financing and capital to fund these needs.

Given these risks, uncertainties and assumptions, the forward-looking events referred to in this presentation may not occur and actual results may differ materially from those expressly or impliedly anticipated in these forward-looking statements. Investors are advised not to place undue reliance on these forward-looking statements.

Investors should assume that the information in this presentation is accurate only as of the date it is issued. Micro-Mechanics (Holdings) Ltd.'s business, financial conditions, results of operations and prospects may have changed since that day. Micro-Mechanics (Holdings) Ltd. has no obligation to update or revise any forward-looking statement, whether as a result of new information, future events or otherwise, except as required by law.



#### **Micro-Mechanics**

31 Kaki Bukit Place Eunos Techpark Singapore 416209 www.micro-mechanics.com

#### **Investor Relations Contact**

Octant Consulting
Tel (65) 6296 3583
herman@octant.com.sg /
lisa@octant.com.sg